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(1) S. H. Freeman, "Microelectronics Technology for Automobile"
Journal of Microelectronics, vol.20, pp. 15-18, April 1996.

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論文送付先

〒167-0042
東京都杉並区西荻北 3-12-2
(社)エレクトロニクス実装学会
ICEP 2009 事務局
TEL: 03-5310-2010
FAX: 03-5310-2011
E mail: icep2009@jiep.or.jp

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35mm

Organic Build-up Package for High Pin Count Chip Application

Paper Title

1 line space

K. Kobayashi, N. Katagiri, S. Wakabayashi, S. Koyama
R&D Dept. Material Process, Shinko
1457-5 Wakaho, Kawada, Nagano-Shi, 381-0103 Japan

Author(s)

Abstract

A build up package consisting of PPE resin (Poly-Phenylene Ether) was developed to mount high pin count chips using flip chip technology. The package was designed to mount 250 μm full grid array chips, therefore the design rule is as follows, line and space are 45 μm, via and via land diameter are 50 μm and 110 μm respectively. The reliability result obtained by environmental tests of the package satisfied all the requirements because a resin used as core and build up dielectric layer is PPE resin which has good moisture stability, low dielectric constant and proper CTE (Coefficient of Thermal Expansion). This paper describes the property of PPE resin, package structure, fabrication process, design and evaluation results of the package.

Abstract (1 column)

23mm

23mm

Introduction

Recently performance of semiconductor chip has been improved remarkably and number of I/O terminal and clock frequency are rapidly increasing mainly in microprocessors and ASICs⁽¹⁾. To assemble such a high pin count chips on package, flip chip interconnect has been introduced.

210mm

7mm

via process to satisfy tough reliability requirements in comparison with existing materials.

Among various kinds of resins, PPE has attractive properties such as low water absorption and low dielectric constant, therefore we chose this material as candidate for packages and tried to modify the properties. PPE resin was improved to get proper CTE and young modulus for build up dielectric layers. (PPE resin has been supplied from Asahi Chemical.)

The package material is changing from ceramic to plastic due to better CTE matching with mother board, lower trace resistance and lower dielectric constant to transmit high frequency signals⁽²⁾. However reliability issues have been big concern to use plastic materials for packages. Recently various kinds of plastic materials have been offered from material suppliers, therefore wider material selection has been expected. Proper material selection for low end, middle end and high end application is available. In the near future, high performance chips will appear and need superior materials for GHz level signal transmission⁽³⁾.

163mm

A build up package consisting of this PPE was developed and applied to a high pin count flip chip application. The reliability results obtained by environmental tests were satisfactory. The package structure, process, resin property, design rule and reliability are described.

Text (2 columns)

Package structure and process

Package structure

Build up layers are laminated on core consisting of several conductive layers with a vacuum hot press.



Fig.1 Cross section feature of build up package

In package manufacturing technology, build up process for PCB becomes more popular because it is easy to make fine circuit patterns. In this process, there are two kinds of methods to make via in insulation layers, one is photo via process using photo imagable resin, another is laser via process using thermosetting resin. The photo process has advantage for mass production ability at low cost, but it lacks for flexibility to modify resin property because photo functional group must exist in resin matrix, on the other hand laser process has advantage for easy modification of resin property but production ability should be improved⁽⁴⁾. In this study we selected a laser

52mm